

3.5 A, 78 mΩ, 2.8 V to 22 V eFuse With Accurate Current Limit, OVP, and Active Reverse Current Blocking



OPERATION DESCRIPTION

The SIP32433A and SIP32433B are single channel eFuses protect both power sources and downstream circuitry from excessive inrush currents, overloads, short circuits, over voltage, and active reverse current blocking which actively suppresses current flowing from the output to the input. They provide increased controllability, reliability, with simplified designs with minimal external components.

V_{IN} overvoltage protection and undervoltage lockout threshold levels can be set with an external resistor network. V_{IN} inrush current can be set with a soft start capacitor. The output current limit can be set by a resistor connected to I_{LIM} pin. I_{LIM} pin voltage can also serve as switch current reporting.

Upon switch-off due to latchable faults, the SIP32433A will latch the power switch off and the PGD will remain low. The switch can restart by resetting the EN or VIN. The SIP32433B will auto retry if there is no OTP or OVP fault. The retry delay time is 32 times the soft start time set by the CSS. The switch is characterized for operation over a junction temperature range of -40 °C to +125 °C.

FEATURES

- 2.8 V to 22 V operation voltage
- 28 V max. DC tolerance on V_{IN}
- 78 mΩ typical switch resistance
- 0.3 A to 4.5 A current limit setting range
- Current limit accuracy of $\pm 8\%$
- Fast short circuit protection response
- OCP triggering without overhead current
- Programmable turn-on slew rate
- Active reverse current blocking
- Adjustable OVP (and fixed 24 V OVP at V_{IN})
- Adjustable UVLO
- Over-temperature protection
- PGD: power good indicator output
- IEC 62368-1 2018, CB certified, E531343-A6001-CB-1
- Compact TDFN10 3 mm x 3 mm package
- 6 A uni-directional parts available with [SIP32434](#)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Industrial
- IoT and smart home
- Medical and healthcare equipment
- Network and telecom equipment
- Data storage, solid state drives
- Computing
- PLC
- Lighting
- Gaming consoles

TYPICAL APPLICATION CIRCUIT

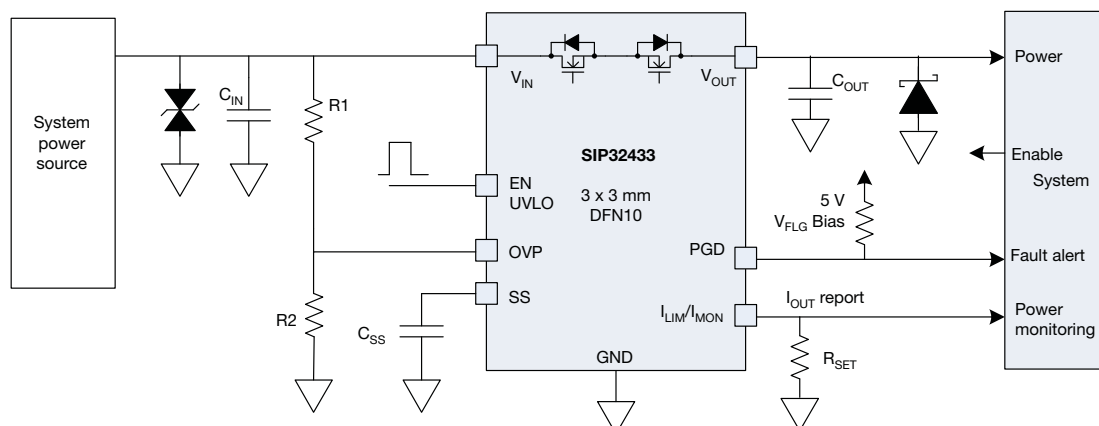


Fig. 1 - Application Circuit

**ORDERING INFORMATION**

PART NUMBER	OCP RESPONSE	$R_{DS(on)}$ (m Ω)	TRUE REVERSE CURRENT BLOCKING	REPORT	MARKING CODE	PACKAGE
SIP32433ADN-T1E4	Latch	78	Yes	PG	2433A	DFN10 3 mm x 3 mm
SIP32433BDN-T1E4	Auto-retry	78	Yes	PG	2433B	DFN10 3 mm x 3 mm
SIP32433AEVB	Evaluation board					
SIP32433BEVB	Evaluation board					

Note

- For AEC-Q100 qualified automotive applications, please refer to SIPQ32433ADN-T1E4 and SIPQ32433BDN-T1E4

ABSOLUTE MAXIMUM RATINGS

PARAMETER	CONDITION	LIMIT	UNIT
Input voltage (V_{IN})	Reference to GND	-0.3 to +28	V
Output voltage (V_{OUT})	Reference to GND	-0.3 to +28	
		-5 V for +5 μ s	
EN voltage	Reference to GND	-0.3 to +24	
OVP	Reference to GND	-0.3 to +6	
SS	Reference to GND	-0.3 to +6	
I_{LIM}		-0.3 to +6	
PGD		-0.3 to +6	
Maximum continuous switch current		3.5	A
Thermal resistance (θ_{thJA})		44.8	$^{\circ}$ C/W
ESD rating	HBM	$\pm$ 1	kV
ESD rating	CDM	$\pm$ 1	
Latch up current	Per JESD78E, Class II	100	mA
Moisture sensitivity level (MSL)		1	
Temperature			
Operating junction temperature		-40 to +150	$^{\circ}$ C
Storage temperature		-65 to +150	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING RANGE

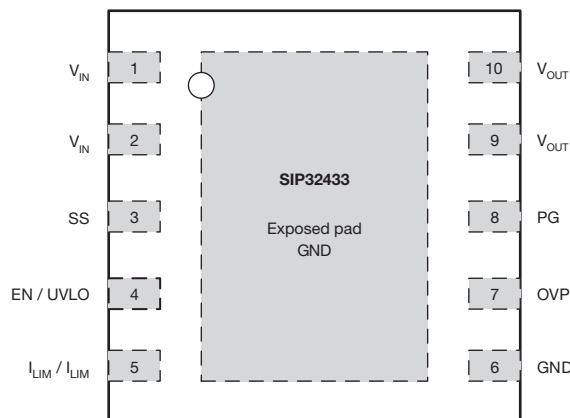
ELECTRICAL	LIMIT	UNIT
Input voltage (V_{IN})	2.8 to 22	V
Operating junction temperature	-40 to +125	$^{\circ}$ C

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS UNLESS SPECIFIED V _{IN} = 12 V, T _J = -40 °C to +125 °C, V _{EN(H)} = 2.4 V, C _{OUT} = 0.1 μF, R _{LIM} = 4.1 kΩ	LIMITS			UNIT
			MIN.	TYP.	MAX.	
Power Supply						
V _{IN} max. DC tolerance	V _{IN(max.)}		-	-	28	V
V _{IN} operation voltage	V _{IN}	Operating input voltage range	2.8	-	22	V
Quiescent current	I _{Q(ON)}	EN = 1.8 V, V _{IN} = 2.8 V to 28 V, V _{OUT} open	-	250	340	μA
Shutdown current	I _{Q(SD)}	V _{IN} = 2.8 V to 28 V, EN = 0 V, T _A = 25 °C	-	0.6	5	
OVP switch-off current	I _{Q(OVP)}	V _{IN} = 2.8 V to 28 V, EN = 2.4 V, OVP = 1.4 V	-	1	-	
V _{IN} UVLO						
Switch V _{OUT} leakage	I _{UVLO_OUT}		-500	-	+500	nA
Switch V _{IN} leakage	I _{UVLO_IN}		-	27	50	μA
Overvoltage Protection						
OVP threshold	V _{OVP}	V _{IN} = 12 V, OVP rising	1.14	1.2	1.26	V
OVP hysteresis	OVP _{HST}		45	105	140	mV
OVP leakage	I _{OVP}	V _{OVP} = 1.2 V on the pin, T _A = 25 °C	-	40	100	nA
V _{IN} pin internal fixed OVP	IN _{OVP}	T _A = 25 °C	22.1	24	25.6	V
EN / UVLO						
EN on threshold	V _{UVPR}	V _{EN} rising	-	1.25	-	V
EN off threshold	V _{UVPF}	V _{EN} falling	-	1.05	-	
EN / UVLO leakage		V _{EN} = 1.2 V	-0.25	-	+0.25	μA
Soft start bias current	I _{SS}		-	5	-	
Overcurrent Protection						
Current limit voltage threshold	V _{OCP}	Voltage that triggers the OCP shown on I _{LIM} pin	-	0.6	-	V
Current limit accuracy	I _{OCP}	V _{IN} - V _{OUT} = 1 V, R _{SET} = 20.6kΩ	0.255	0.3	0.345	A
		V _{IN} - V _{OUT} = 1 V, R _{SET} = 4.1 kΩ	1.39	1.5	1.6	
		V _{IN} - V _{OUT} = 1 V, R _{SET} = 1.8 kΩ	3.32	3.5	3.68	
Current limit setting range			0.25	-	4.5	
Current limit hold-up time	t _{LIM}	Current limiting timeout, if no OTP	4	6	8	ms
Active ReverseCurrent Blocking						
V _{IN} - V _{OUT} reverse blocking falling threshold	V _{REVTH}	V _{IN} - V _{OUT} , V _{IN} falling	-30	-20	-5	mV
V _{IN} - V _{OUT} reverse blocking rising threshold	V _{FWDTH}	V _{IN} - V _{OUT} , V _{IN} rising	5	20	30	
Power Switch						
On resistance	R _{DS(ON)}	V _{IN} = 3 V to 22 V, I _{OUT} = 1 A, T _J = 25 °C	-	78	100	mΩ
		V _{IN} = 3 V to 22 V, I _{OUT} = 1 A, T _J = 85 °C	-	-	130	
Output leakage at switch off		V _{IN} = 28 V, V _{EN} = 0 V, V _{OUT} = 0 V, sourcing	-	-	5	μA
PGD, Power Good						
PGD pull-down resistance	R _{PG}	V _{IN} = 5 V, output pin = 0.1 V	-	5.2	10	Ω
PGD oII leakage	I _{PG}	Biased with 5 V _{DC}	-	0.01	1	μA



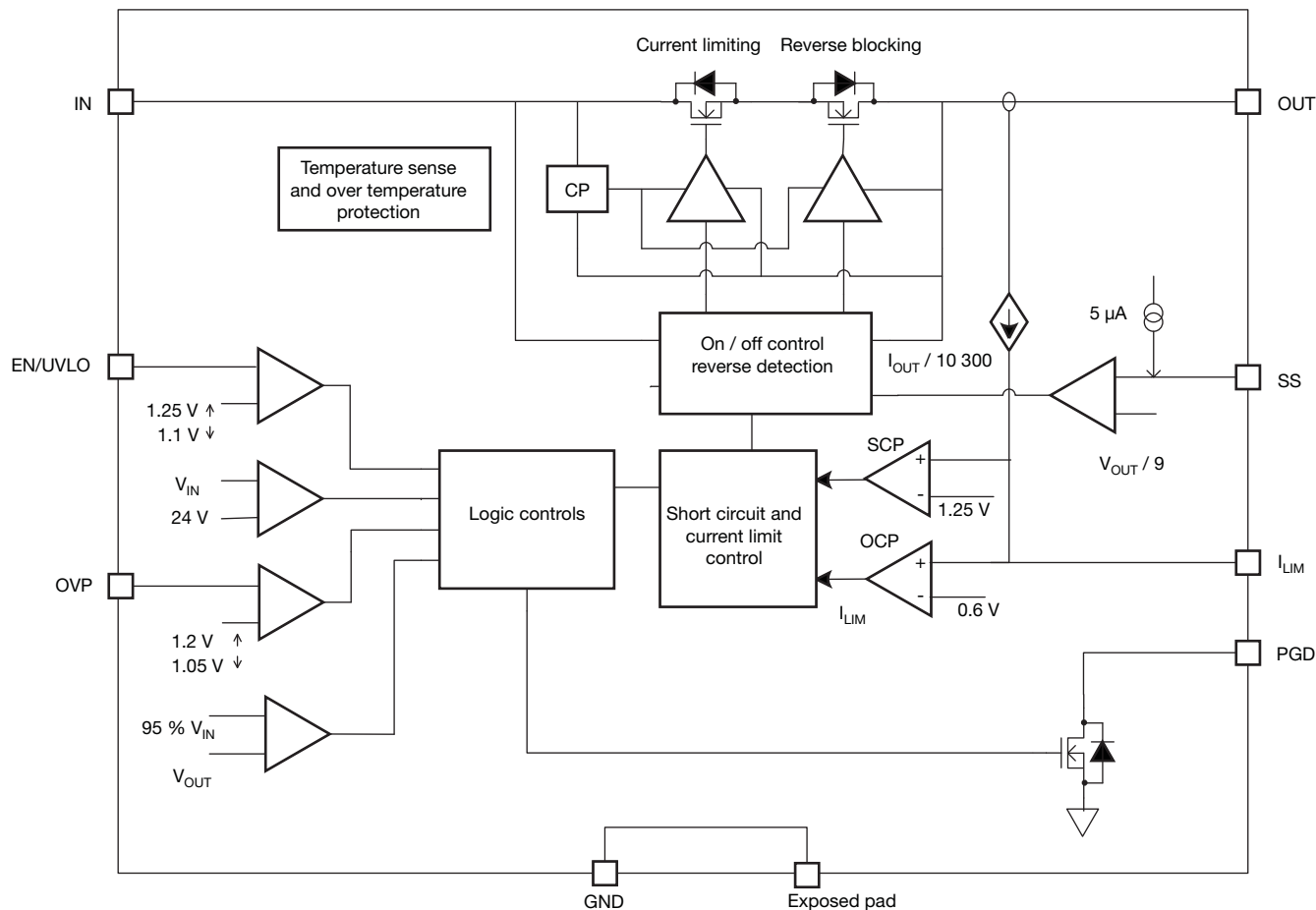
SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS UNLESS SPECIFIED V _{IN} = 12 V, T _J = -40 °C to +125 °C, V _{EN(H)} = 2.4 V, C _{OUT} = 0.1 μF, R _{LIM} = 4.1 kΩ	LIMITS			UNIT
			MIN.	TYP.	MAX.	
EN / UVLO						
Switch turn-on delay time	T _{ON_DLY}	From EN / UVLO voltage, V _{UVPR} to V _{OUT} reaches 10 % V _{IN} , R _L = 10 Ω, C _L = 10 μF, C _{SS} open	-	190	-	μs
Shutdown delay	T _{OFF_DLY}	From EN / UVLO low to V _{OUT} = 0.9 x V _{IN} , R _L = 10 Ω, C _L = 10 μF, C _{SS} open	-	10	-	
OVP Timing						
OVP off time	t _{OVP}	R _L = 100 Ω, C _L = 0 μF, OVP steps from 1 V to 1.4 V; measured from OVP pin voltage crossing 1.2 V threshold to V _{OUT} = 0.9 x V _{IN}	-	0.3	1	μs
Internal OVP off time	t _{OVP_INT}	R _L = 100 Ω, C _L = 0 μF, V _{IN} steps from 22 V to 26 V; measured from V _{IN} pin voltage crossing 24 V threshold to V _{OUT} = 0.9 x V _{IN}	-	1.5	-	
Flag reporting delay		PGD pull up to 5 V through a 100 kΩ; delay time from OVP pin voltage step to PGD is below 0.5 V	-	-	2	
Overcurrent protection						
Moderate overcurrent protection	t _{OCP}	Load current is 120 % of current limit threshold	-	1.1	-	μs
Soft Start Control						
Output rise up time	t _R	V _{IN} = 12 V, R _L = 10 Ω, C _L = 10 μF, V _{OUT} from 10 % to 90 % V _{IN} , C _{SS} open	-	350	-	μs
		V _{IN} = 12 V, R _L = 10 Ω, C _L = 10 μF, V _{OUT} from 10 % to 90 % V _{IN} , C _{SS} = 22 nF	-	4.7	-	ms
SS charge current			-	5	-	μA
Auto Retry						
Auto retry count	RTY _{cnt}	Delay time of restart after all faults are removed; this is defined as the number of cycles of soft start time set by C _{SS}	-	32	-	
Thermal Shutdown						
Thermal shutdown		Temperature increases	-	165	-	°C
Thermal shutdown hysteresis			-	45	-	°C

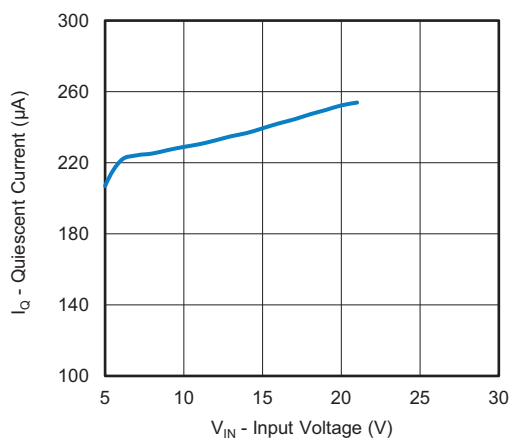
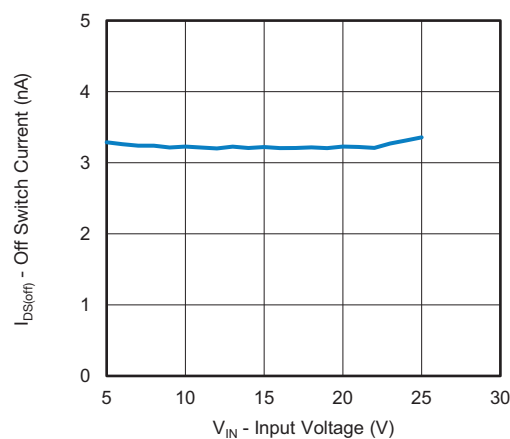
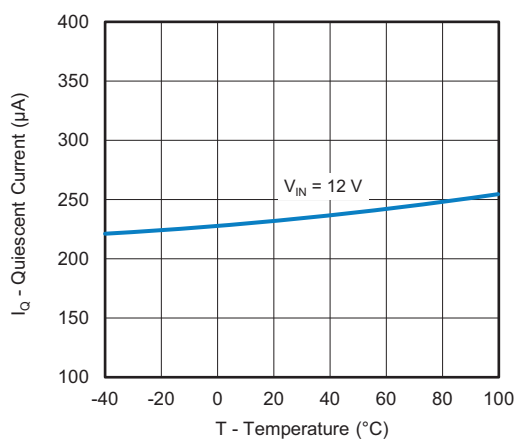
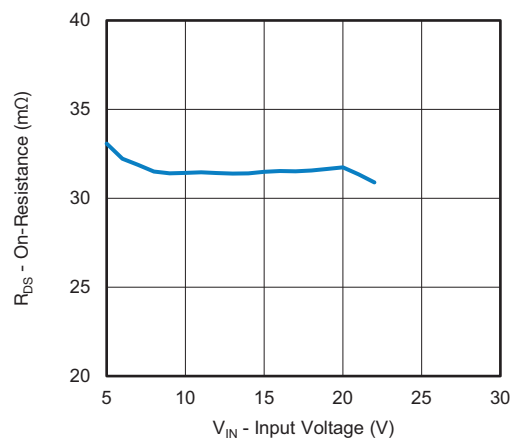
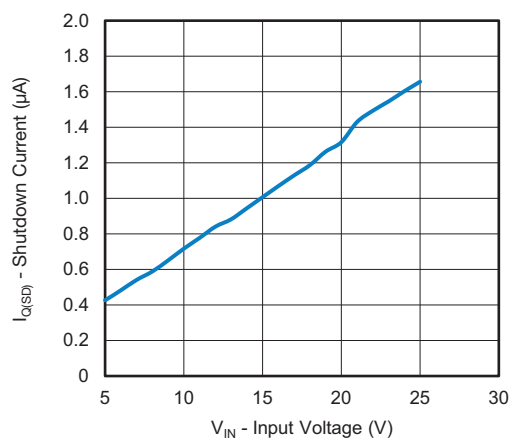
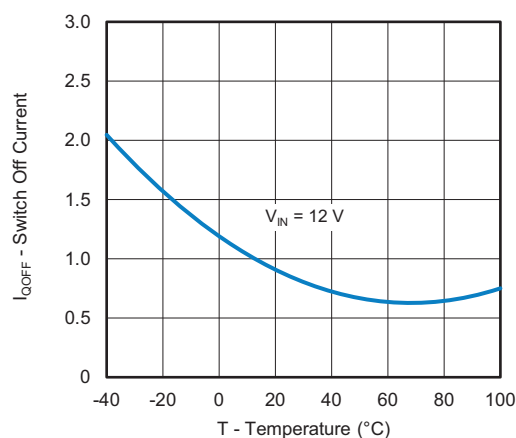
PACKAGE OUTLINE

Fig. 2 - Pin Out Drawing (top view)

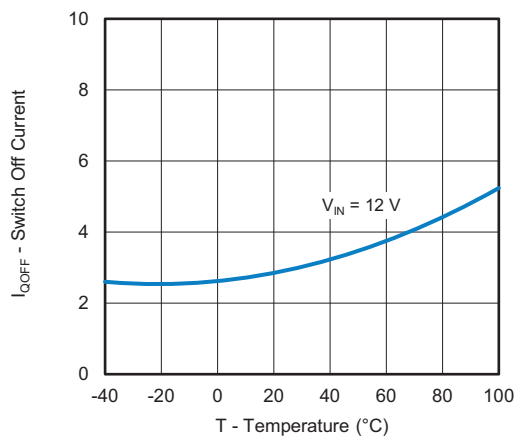
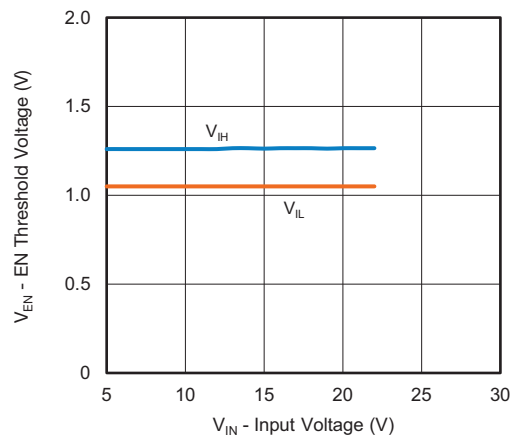
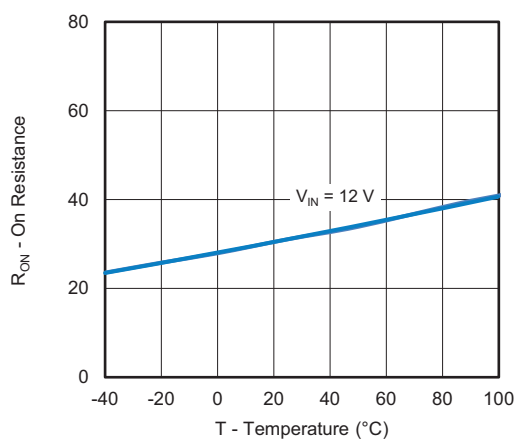
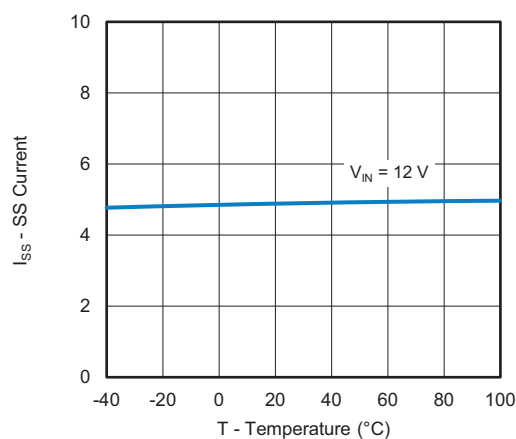
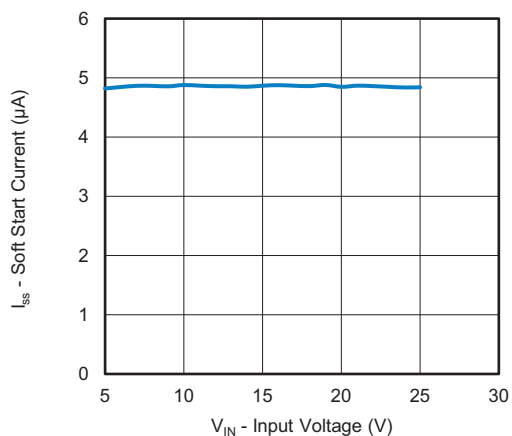
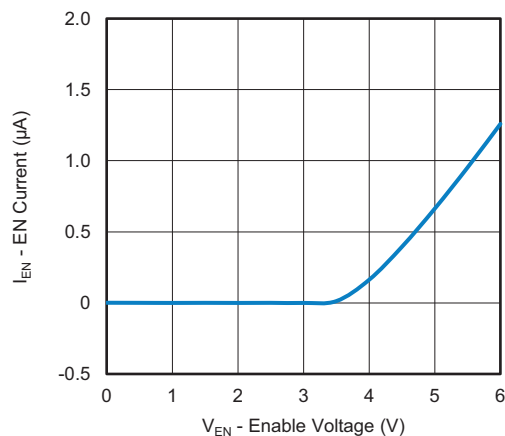
PIN DESCRIPTION		
PIN #	NAME	FUNCTION
1, 2	V_{IN}	Power switch input pins; two pins are fused inside the package
3	SS	A capacitor from this pin to GND sets output voltage slew rate
4	EN / UVLO	Active high switch control input; $V_{THL} < 0.3 V$, $V_{THH} > 1.4 V$
5	I_{LIM} / I_{MON}	A resistor from this pin to GND sets the overload and short-circuit current limit; the pin can be used for current reporting, referring to the voltage developed over the current limit setting resistor
6	GND	Ground
7	OVP	Input for setting the programmable overvoltage protection threshold. An overvoltage event turns-off the internal FET and asserts FLT to indicate the overvoltage fault
8	PGD	Open drain output, when V_{OUT} is $\geq 95 \% V_{IN}$, and none of the following faults are triggered: OT, OC, OV
9, 10	V_{OUT}	Power switch output pins; two pins are fused inside the package
Exposed pad	GND	The package's central exposed pad must be connected to the ground plane; optimal PCB thermal design will enhance device performance

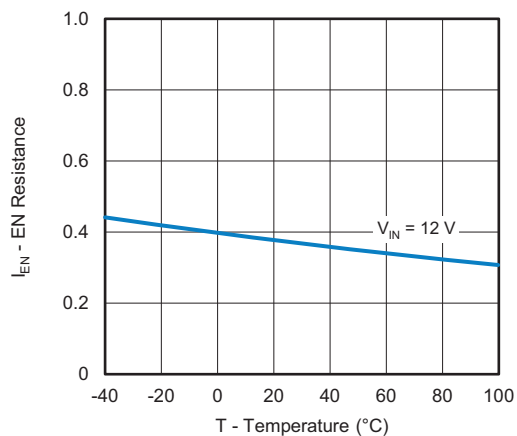
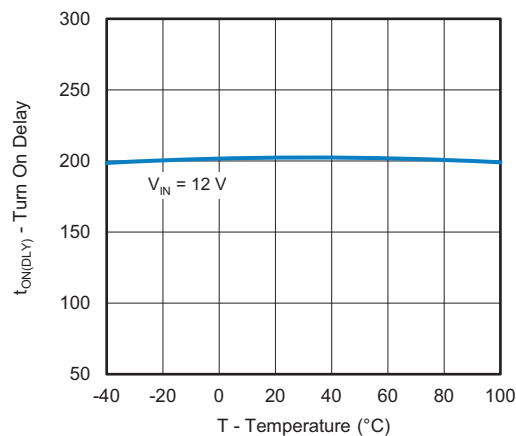
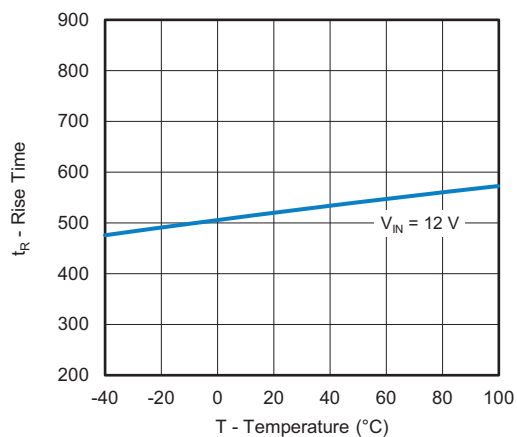
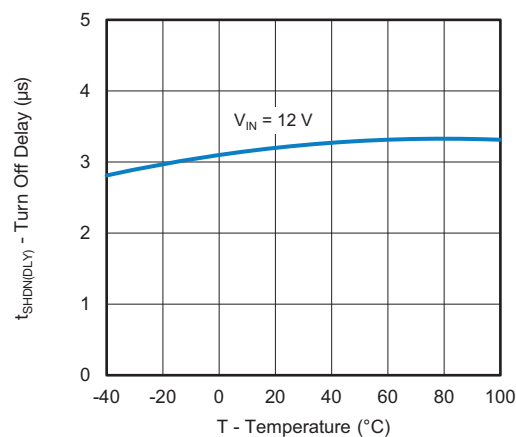
FUNCTIONAL BLOCK DIAGRAM AND TRUTH TABLE

TRUTH TABLE	
EN	SWITCH
1	ON
0	OFF


Fig. 3 - Device Block Diagram


Fig. 4 - Quiescent Current vs. Input

Fig. 7 - Switch Off Current vs. Input

Fig. 5 - Quiescent Current vs. Temperature

Fig. 8 - On Resistance vs. Input

Fig. 6 - Shutdown Current vs. Input

Fig. 9 - Shutdown Current vs. Temperature


Fig. 10 - Switch Off Current vs. Temperature

Fig. 13 - Threshold Voltage vs. Input Voltage V_{IN}

Fig. 11 - On Resistance vs. Temperature

Fig. 14 - Soft Start Current vs. Temperature

Fig. 12 - Soft Start Current vs. Input Voltage V_{IN}

Fig. 15 - EN Current vs. EN Voltage


Fig. 16 - Enable Resistance vs. Temperature

Fig. 18 - Turn On Delay Time vs. Temperature

Fig. 17 - Rise Time vs. Temperature

Fig. 19 - Turn Off Delay Time vs. Temperature

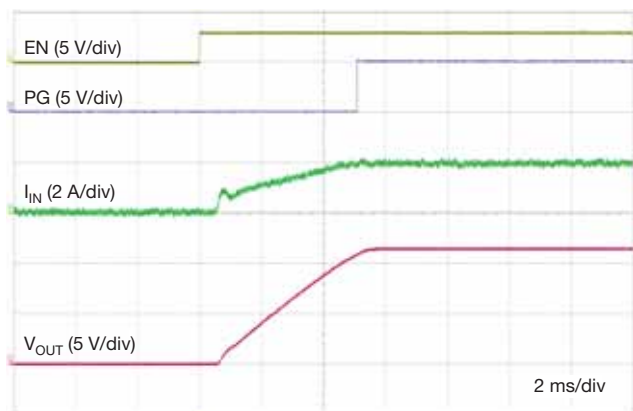
TYPICAL CHARACTERISTICS


Fig. 20 - Turn On by EN
 $V_{IN} = 12\text{ V}$, $R_L = 6\ \Omega$, $C_L = 47\ \mu\text{F} \times 3$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

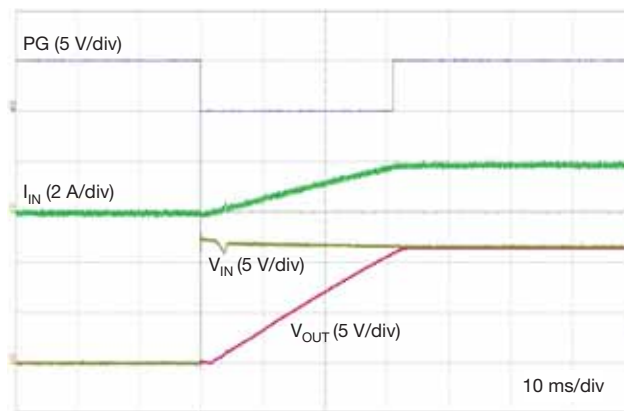


Fig. 23 - Turn On by Hot-Plug of V_{IN}
 $V_{IN} = 12\text{ V}$, $R_L = 6\ \Omega$, $C_L = 47\ \mu\text{F} \times 3$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$
 EN Voltage Divider Resistors, $1\text{ M}\Omega$ and $133\text{ k}\Omega$

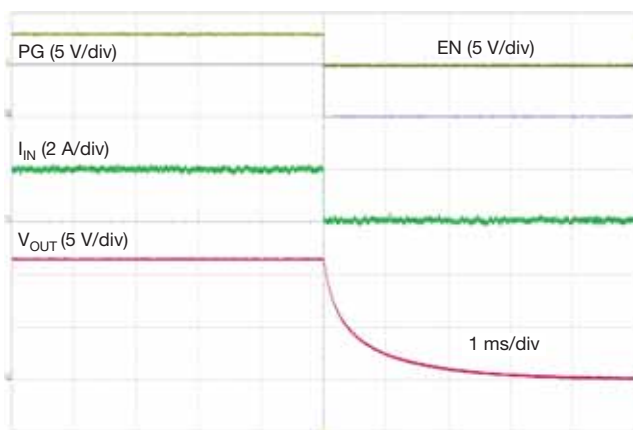


Fig. 21 - Turn Off by EN
 $V_{IN} = 12\text{ V}$, $R_L = 6\ \Omega$, $C_L = 47\ \mu\text{F} \times 3$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

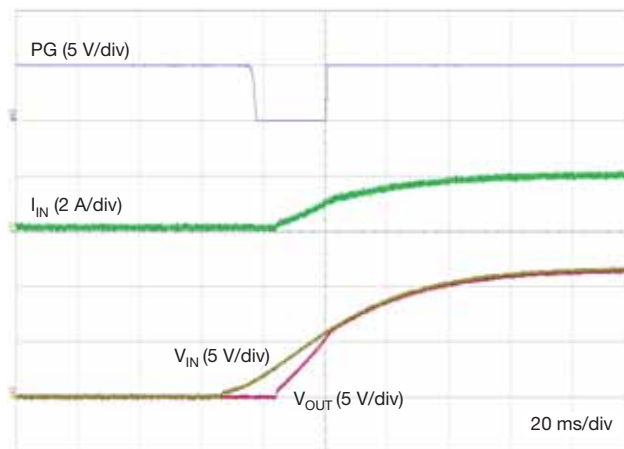


Fig. 24 - Turn On by V_{IN} When EN is 3 V
 $V_{IN} = 12\text{ V}$, $R_L = 6\ \Omega$, $C_L = 47\ \mu\text{F} \times 3$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

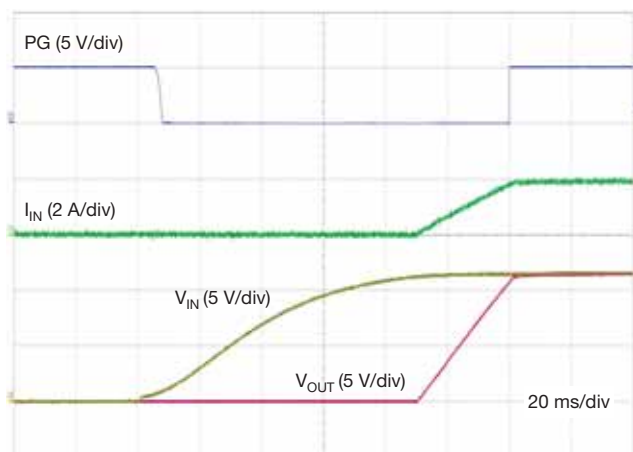


Fig. 22 - Turn On by V_{IN}
 $V_{IN} = 12\text{ V}$, $R_L = 6\ \Omega$, $C_L = 47\ \mu\text{F} \times 3$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$
 EN Voltage Divider Resistors, $1\text{ M}\Omega$ and $133\text{ k}\Omega$

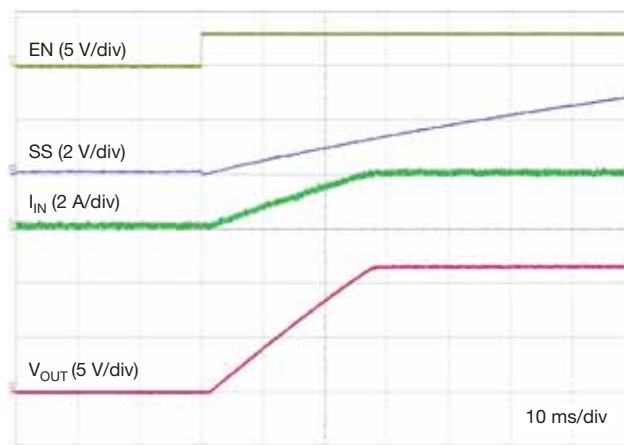


Fig. 25 - Turn On by EN Into Resistive Load
 $V_{IN} = 12\text{ V}$, $R_L = 6\ \Omega$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

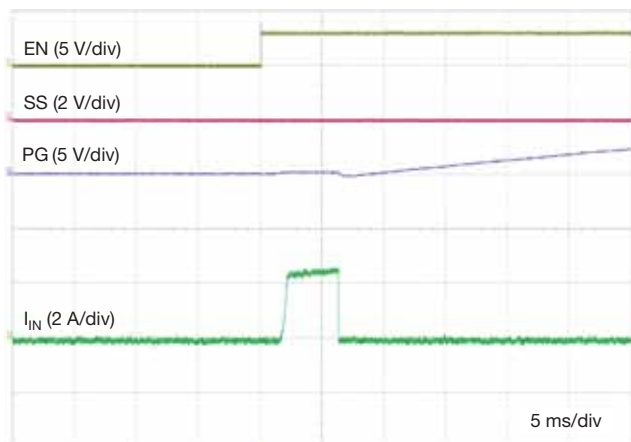


Fig. 26 - Turn On Into Output Short
 $V_{IN} = 12\text{ V}$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

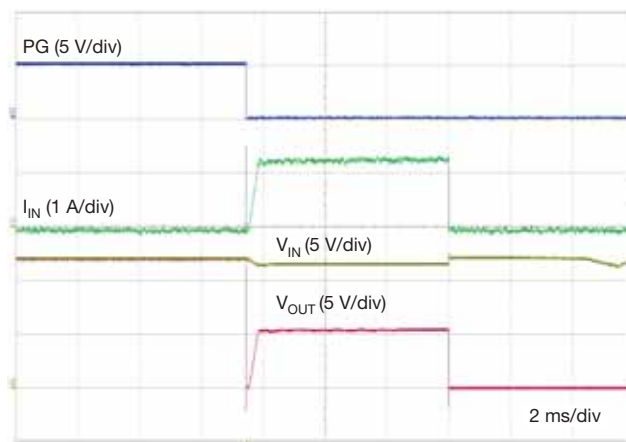


Fig. 29 - V_{OUT} Short With a $2\text{ }\Omega$ Load
 $V_{IN} = 12\text{ V}$, $R_L = 2\text{ }\Omega$, $C_L = 0\text{ }\mu\text{F}$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

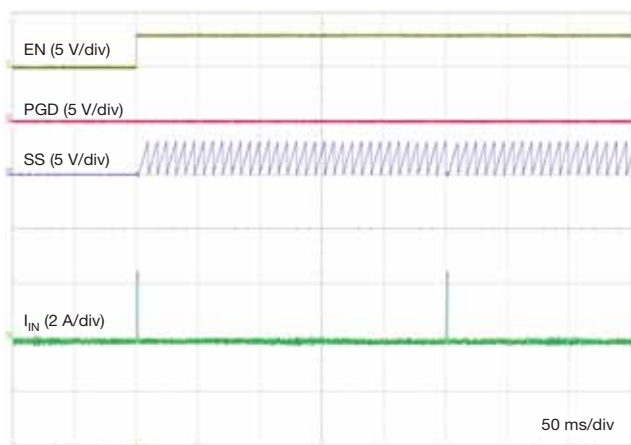


Fig. 27 - Turn On Into Output Short, Auto-Retry
 $V_{IN} = 12\text{ V}$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

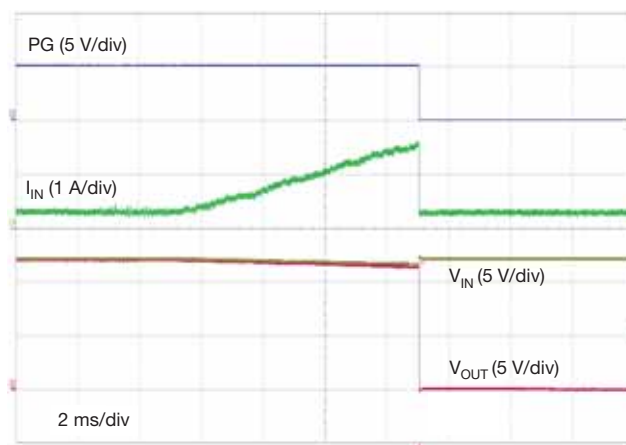


Fig. 30 - Output Current Protection
Increase Load Current Slowly
 $V_{IN} = 12\text{ V}$, $R_L = 2\text{ }\Omega$, $C_L = 47\text{ nF}$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$

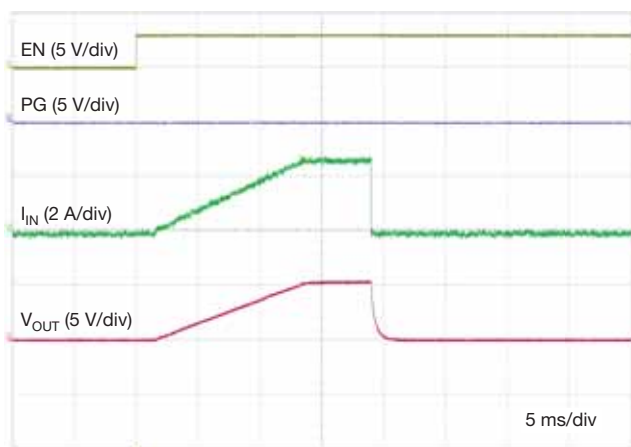


Fig. 28 - Turn On by EN Into OCP Load
 $V_{IN} = 12\text{ V}$, $R_L = 2\text{ }\Omega$, $C_L = 47\text{ }\mu\text{F} \times 3$, $C_{SS} = 133\text{ }\mu\text{F}$, $R_{LIM} = 2.49\text{ k}\Omega$

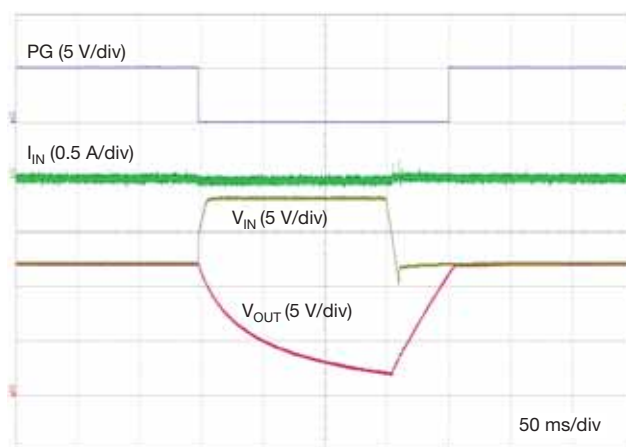


Fig. 31 - Over Voltage Protection
 $R_L = 1\text{ k}\Omega$, $C_L = 100\text{ }\mu\text{F}$, $C_{SS} = 133\text{ nF}$, $R_{LIM} = 2.49\text{ k}\Omega$,
OVP Set to 18 V

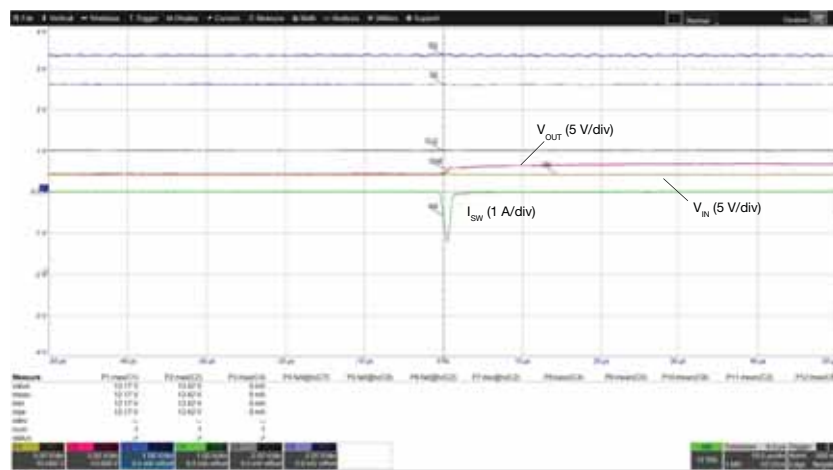


Fig. 32 - Active Reverse Current Blocking
 $V_{IN} = 12\text{ V}$, V_{OUT} Raised Up to 13.5 V

OPERATION

The SIP32433A and SIP32433B are $78\text{ m}\Omega$ switches designed to operate in the 2.8 V to 22 V range. The V_{IN} maximum DC tolerance is 28 V .

The devices start their operation by checking the V_{IN} , V_{OUT} , OVP, and EN / UVLO pins. When the voltages are within the operation ranges, the PGD open drain switch is off. The PGD is high through an external pull high resistor. A high level on the EN / UVLO pin turns on the soft start current source charging CSS and enables internal MOSFET gate driver control the V_{OUT} to follow SS voltage at 9 times ratio. In case of OCP during soft start, the switch current will be regulated to the set current limit level.

After a successful turn-on sequence, the device now actively monitors its load current, input voltage, and protects the load from harmful over-current, and over-voltage conditions. A built-in thermal sense circuit will detect junction over temperature and shut down the switch for safety.

SWITCH ON / OFF, AND UNDER-VOLTAGE LOCKOUT PROTECTION - UVLO

EN / UVLO pin controls the on / off of the power switch. When EN / UVLO is at a logic high the switch is on. When EN / UVLO is at a logic low, the switch is off.

The SIP32433A and SIP32433B implement under-voltage protection on the EN / UVLO to turn off the output. It is a user-defined under-voltage protection setting to flexibly select the proper minimum applied voltage for the downstream load or the device's proper operation.

The diagram shows how a resistor divider from supply to GND can be used to set the UVLO set point for a given voltage supply level.

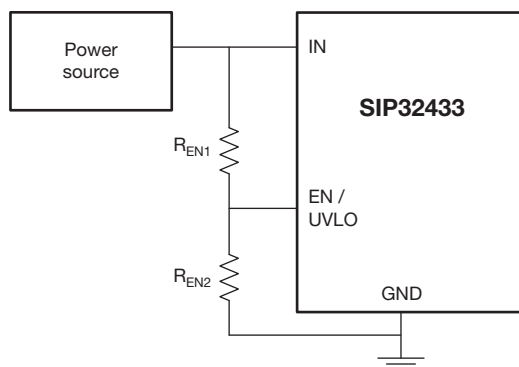


Fig. 33

The resistors must be sized large enough to minimize the constant leakage from supply to ground through the resistor divider network. At the same time, keep the current through the resistor network sufficiently larger than the leakage current on the EN / UVLO pin to minimize the error in the resistor divider ratio.

$$R_{EN1} = \frac{R_{EN2}(V_{IN} - V_{UVPR})}{V_{UVPR}}$$

Where V_{UVPR} is 1.25 V.

UVLO turn off delay (T_{OFF_DLY}) is typically 550 μ s and turn on delay T_{ON_DLY} is typically 500 μ s.

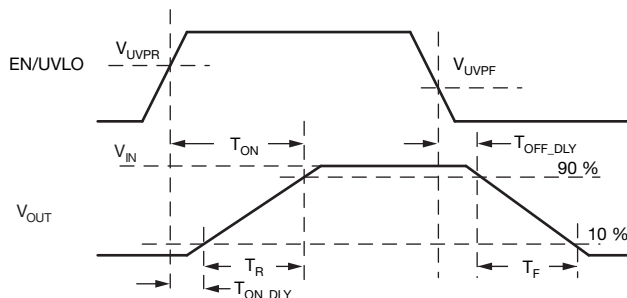


Fig. 34 - Switching Times

INRUSH CURRENT, AND OVER-CURRENT PROTECTION

The SIP32433A and SIP32433B incorporate two protections against over-current:

- Adjustable slew rate (SR) for inrush current control
- Adjustable over-current protection / active current limit to protect against overload conditions

The over-current protection (OCP) is active also during soft start. The over-current protection circuit controls the switch impedance to limit the current to the level programmed by the R_{SET} resistor.

If the over-current condition persists for more than 6 ms (typ.), the switch shuts off and alert the drain FLG is asserted, pulling the pin to GND.

SLEW RATE CONTROL

An inrush current happens when the switch turns on into a large output capacitance. If the inrush current is not controlled, it can damage the input connectors and / or cause the system power supply to droop, leading to unexpected restarts elsewhere in the system.

The SiP32433A and SiP32433B provide integrated output slew rate control to manage the inrush current during start-up. This is achieved by forcing the V_{OUT} to follow the voltage on a soft start capacitor. A constant current source of 5 μA charges the C_{SS} , generating a linear ramp up voltage on C_{SS} .

$$V_{OUT} = 9 \times V_{SS}$$

The inrush current is proportional to the load capacitance and rising slew rate. The following equations can be used to calculate the C_{SS} and slew rate required to limit the inrush current (I_{INRUSH}) for a given load capacitance (C_{OUT}):

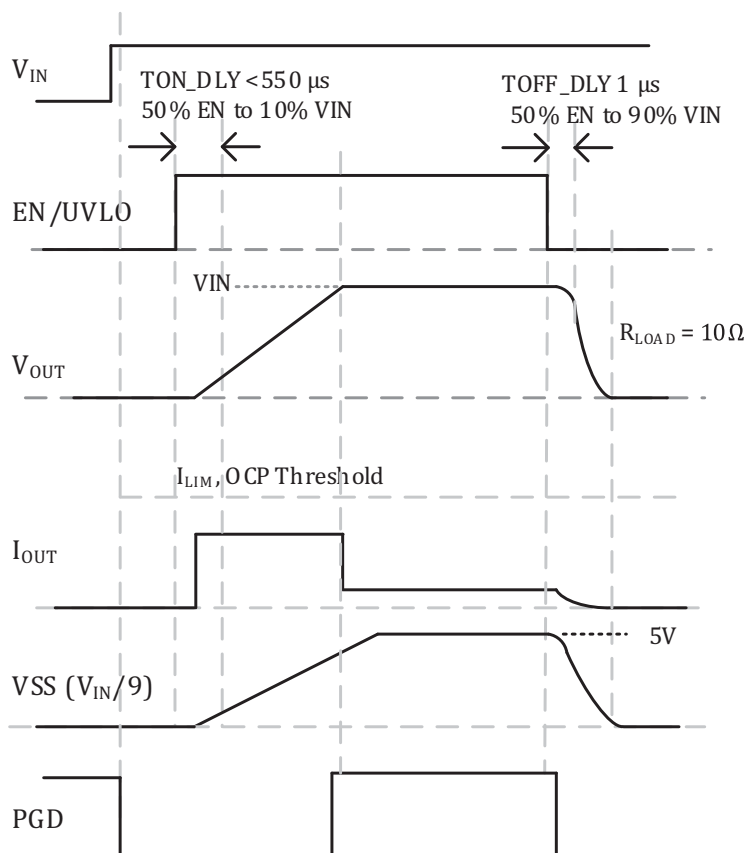
$$SR \text{ (V/ms)} = \frac{I_{INRUSH} \text{ (mA)}}{C_{OUT} \text{ (}\mu\text{F)}}$$

$$SR = \frac{I_{SS}}{C_{SS}} \times 9$$

$$T_{SS} = \frac{V_{IN}}{SR} = V_{IN} \times \frac{C_{OUT} \text{ (}\mu\text{F)}}{I_{INRUSH} \text{ (mA)}}$$

Inrush current should be controlled well below 20 % of set current limit, and within the device SOA.

The fastest output slew rate is achieved by leaving the soft start pin open.



PGD is pulled through a resistor to an external voltage source

Fig. 35

CURRENT LIMIT SETTING

The SIP32433A and SIP32433B actively monitor the current flow through the switch and provide a quick response to over-current conditions by actively regulating the current to a set limit. The current limit is set by connecting a resistor between the I_{LIM} pin and GND. R_{SET} can be calculated by the following formula for a desired current limit:

$$I_{LIM} = \frac{V_{OCP}}{R_{SET}} \times 10\,300$$

V_{OCP} is 0.6 V.

When the load current exceeds the threshold (I_{LIM}), the parts respond within 1 μ s (typ.) to turn off the switch and then regulate the switch gate voltage to limit the output current to the set I_{LIM} level. During this brief period before the over-current protection circuit is engaged, the parts will see a surge current, especially under a severe output short condition. The magnitude of the surge current developed during the period when the over-current protection is not engaged is determined by impedance in the loop from the input current source to ground and the response time. This impedance is the sum total of the current source impedance, the path resistance and inductance, and the load impedance.

If the over-current condition persists for more than 6 ms / typ., the switch shuts off. When V_{OUT} falls below 95 % of V_{IN} , the PGD is pulled low. The device will exit current limiting when the load current falls below I_{LIM} before the end of the current limit period. The control circuit will increase the gate drive in the same manner as the soft start when the switch exits from the current limit mode.

The I_{LIMIT} / I_{MON} pin can also be used for current reporting. The output path should be of high impedance to prevent any disruption to the current limit circuitry.

The current limit mode could result in excessive power on the switch, which increases the T_J quickly. The SIP32433A and SIP32433B have OTP, providing an enhanced level of protection.

Once the device is off due to OCP or OTP faults, the SIP32433A stays in the latch-off state and the SIP32433B auto-retries after 32 times of the programmed soft start time. They can be reset by toggling V_{IN} or EN / UVLO.

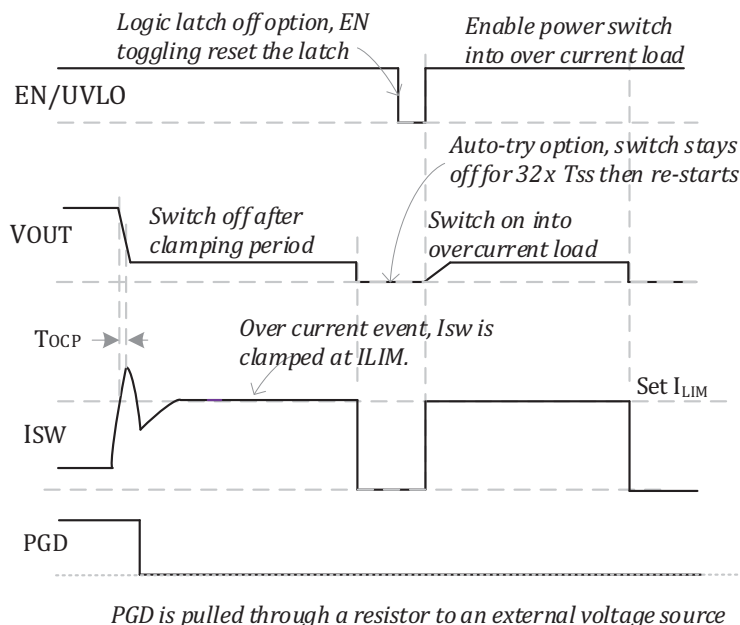


Fig. 36 - Over-Current Protection

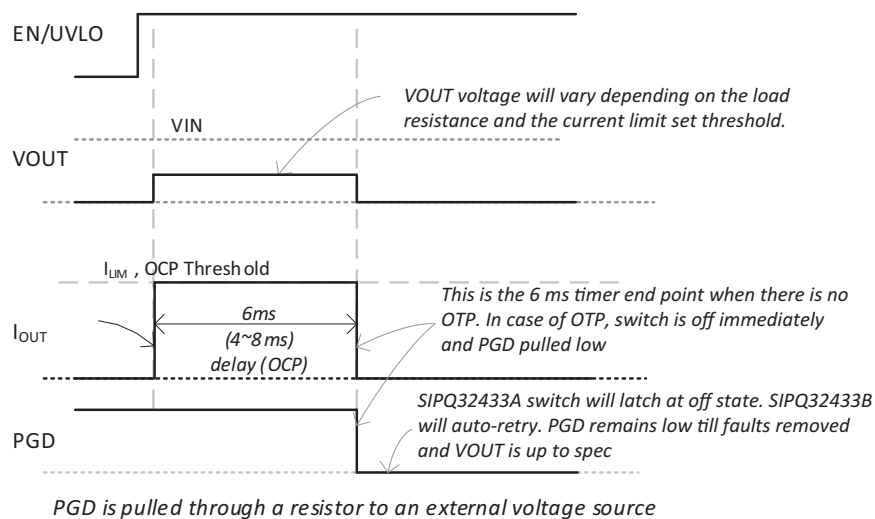
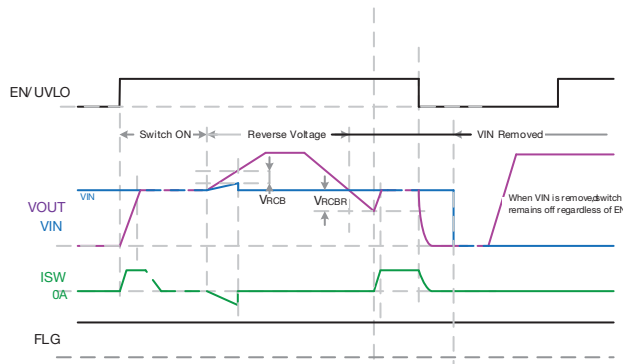


Fig. 37 - Turn On Into Over-Current Load

Active Reverse Current Blocking

The SiP32433A and SiP32433B feature ARCB (active reverse current blocking) ideal diode operation. When V_{OUT} is detected higher than V_{IN} by V_{RCB} (20 mV typ.) the switch is turned off. The TRCB response time t_{RCB} is 300 ns ($V_{OUT} - V_{IN} = 100$ mV) and 3 μ s ($V_{OUT} - V_{IN} = 3$ mV). TRCB is a non-latchable fault. Once V_{OUT} falls below the TRCB recovery threshold (V_{RCBR} 20 mV typically), the switch will turn on without soft start procedure. The SiP32433A and SiP32433B also block the current from V_{OUT} to V_{IN} when V_{IN} is short to GND. When the switch is disabled, current flow is blocked in both directions.



FLG remains high on this event

Fig. 38 - Active Reverse Current Blocking

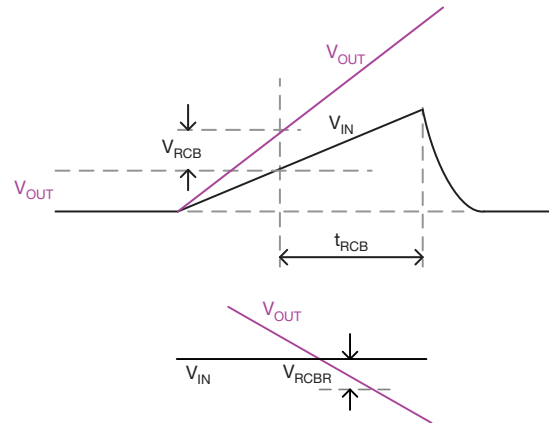


Fig. 39 - Active Reverse Current Blocking

OVER-VOLTAGE PROTECTION (OVP)

The SiP32433A and SiP32433B implement overvoltage protection (OVP) on both the V_{IN} and OVP pins to protect the output load in the event of an input over-voltage. When the input exceeds the over-voltage protection thresholds $V_{OVP(R)}$ or the IN_{OVP} , which is typically 24 V, the device turns off the output within t_{OVP} , while the open drain PGD asserts in the meantime. As long as an over-voltage condition is present on the input, the device stays disabled with the output turned off. Over-voltage is a non-latchable fault. Once the input voltage returns to the normal operating range, the device attempts to start up normally.

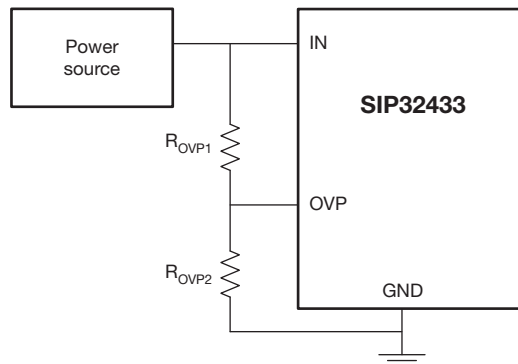


Fig. 40

$$\frac{R_{OVP1}}{R_{OVP2}} = \frac{V_{IN(OVP)} - 1.2 \text{ V}}{1.2 \text{ V}}$$

OVP voltage divider resistors total resistance should not be over 2.5 M Ω .

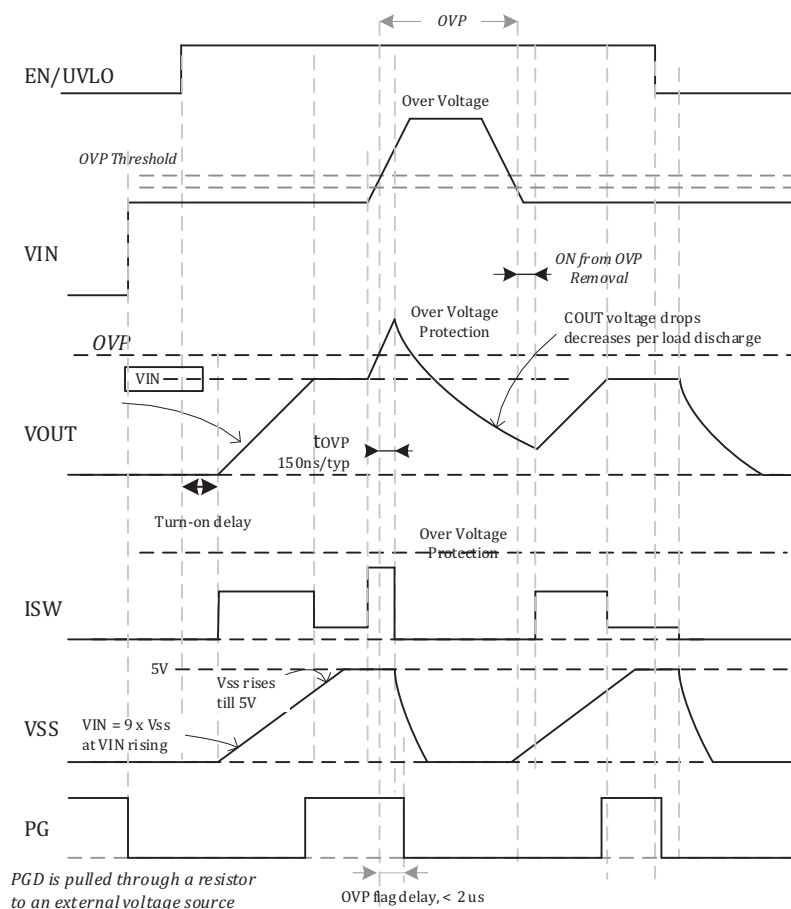


Fig. 41 - Over-Voltage Protection

OTP, OVER-TEMPERATURE PROTECTION

Over-temperature protection turns off the power switch when the die temperature reaches the OTP threshold of 165 °C. The hysteresis is 45 °C. When the die temperature drops below 120 °C, it is allowed to turn on again.

PGD, POWER GOOD REPORTING

PGD is an open drain output. Connect an external pull-up resistor to 3.3 V or 5 V.. It is asserted low when V_{OUT} is below 95 % of V_{IN} , an over-current, over-voltage, or over-temperature fault condition occurs.

INPUT CAPACITOR

A 2.2 μF or larger C_{IN} is recommended. It should be placed as physically close to the device's input pins and ground to be effective to minimize transients on the input. Ceramic capacitors are recommended over tantalum because of their ability to withstand input current surges from low impedance sources such as batteries. For hot-plug applications, where input path inductance is negligible, this input capacitor can be minimized or eliminated.

OUTPUT CAPACITOR

The SIP32433A and SIP32433B do not require an output capacitor for proper operation. Still, a proper value C_{OUT} is recommended to accommodate load transient per circuit design requirements. There are no ESR or capacitor type requirements.

Protection

LAYOUT GUIDELINES

The SiP32433A and SiP32433B are protection switches designed to maintain a constant output load current upon over-current fault. Optimized layout with efficient heat sinking is critical. It is recommended to put as much copper as possible to the devices' central exposed pad which is connected to ground. Connect all ground planes with all possible thermal VIAs.

The circuit setting components should be laid close to their connection pins. The components include current limit setting resistor, soft start setting capacitor, and resistors connected to EN / UVLO and OVP pins.

Protection devices such as input TVS or output Schottky diodes must be located close the pins to be protected and routed with short traces to reduce inductance.

Below is a layout example.

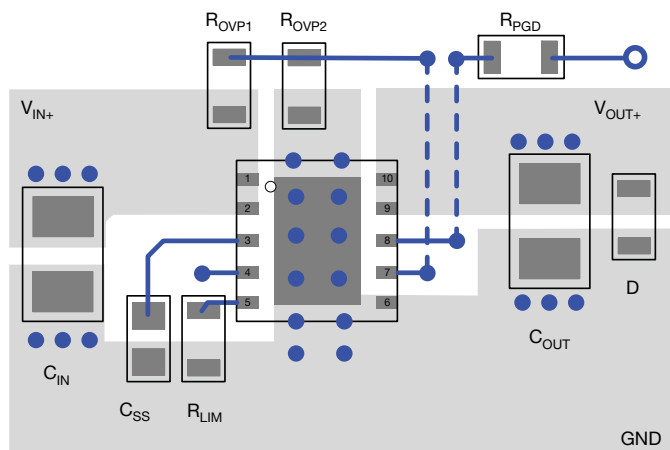


Fig. 42

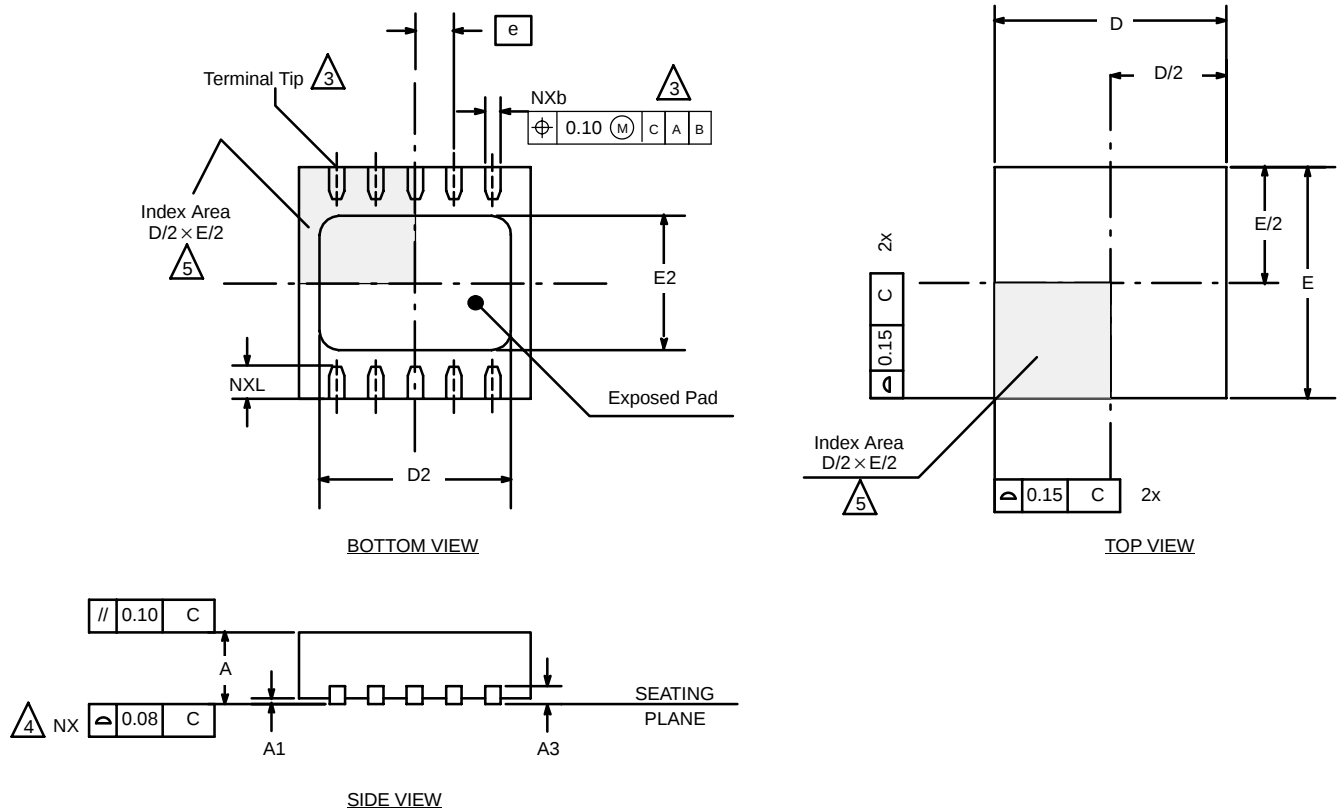
**PRODUCT SUMMARY**

Part number	SiP32433A	SiP32433B
Description	3.5 A, 78 Ω current limit, OVP, and active reverse current blocking, latch-off on fault	3.5 A, 78 m Ω , 2.8 V to 22 V eFuse with accurate current limit, OVP, and active reverse current blocking, auto retry on fault
Configuration	Single	Single
Slew rate time (μ s)	Adjustable	Adjustable
On delay time (μ s)	190	190
Input voltage min. (V)	2.8	2.8
Input voltage max. (V)	28	28
On-resistance at input voltage min. (m Ω)	78	78
On-resistance at input voltage max. (m Ω)	78	78
Quiescent current at input voltage min. (μ A)	180	180
Quiescent current at input voltage max. (μ A)	250	250
Output discharge (yes / no)	N	N
Reverse blocking (yes / no)	Y	Y
Continuous current (A)	3.5	3.5
Package type	DFN33-10L	DFN33-10L
Package size (W, L, H) (mm)	3.0 x 3.0 x 0.9	3.0 x 3.0 x 0.9
Status code	2	2
Product type	Slew rate, current limit	Slew rate, current limit
Applications	Computers, consumer, industrial, healthcare, networking, portable	Computers, consumer, industrial, healthcare, networking, portable

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DFN-10 LEAD (3 X 3)



NOTES:

1. All dimensions are in millimeters and inches.

2. N is the total number of terminals.

3. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30 mm from terminal tip.

4. Coplanarity applies to the exposed heat sink slug as well as the terminal.

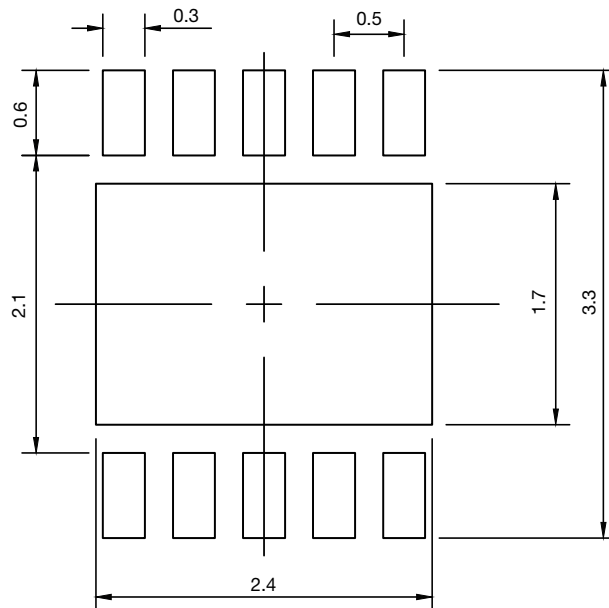
5. The pin #1 identifier may be either a mold or marked feature, it must be located within the zone indicated.

Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.80	0.90	1.00	0.031	0.035	0.039
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 BSC			0.008 BSC		
b	0.18	0.23	0.30	0.007	0.009	0.012
D	3.00 BSC			0.118 BSC		
D2	2.20	2.38	2.48	0.087	0.094	0.098
E	3.00 BSC			0.118 BSC		
E2	1.49	1.64	1.74	0.059	0.065	0.069
e	0.50 BSC			0.020 BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020
*Use millimeters as the primary measurement.						
ECN: S-42134—Rev. A, 29-Nov-04						
DWG: 5943						

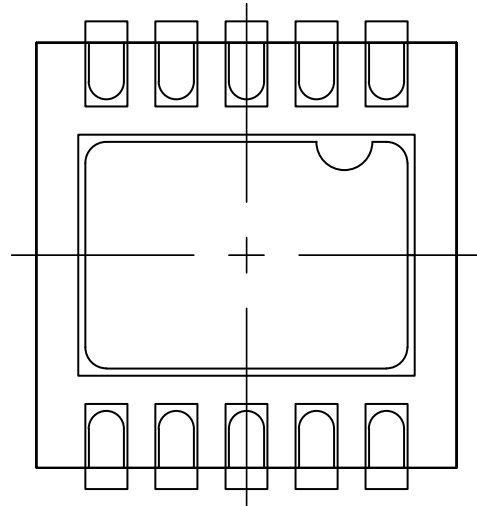


Recommended Minimum PAD for DFN10 3 mm x 3 mm

Recommended Land Pattern



Recommended Land Pattern vs. Case Outline



Note: Dimension are in millimeters

ECN: S22-0379-Rev. A, 02-May-2022
DWG: 3008



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